

Description

The VSM3008Y uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge .This device is suitable for use as a Battery protection or in other switching application.

General Feature

V_{DS} =30V,I_D =8A

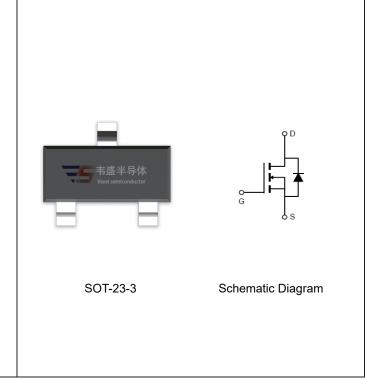
 $R_{DS(ON)}$ <17m Ω @ V_{GS} =10V

 $R_{DS(ON)}$ < 22m Ω @ V_{GS} =4.5V

- High Power and current handing capability
- Lead free product is acquired
- Surface mount package

Application

- Battery switch
- ●DC/DC converter



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
VSM3008Y-S2	VSM3008Y	SOT-23-3	Ø180mm	8 mm	3000 units

Absolute Maximum Ratings (T_A=25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	30	V
Gate-Source Voltage	V _G s	±20	V
Drain Current-Continuous	I _D	8	А
Drain Current-Pulsed (Note 1)	I _{DM}	30	Α
Maximum Power Dissipation	P _D	1.5	W
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 150	$^{\circ}$

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{ hetaJA}$	83.3	°C/W

Electrical Characteristics (T_A=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit	
Off Characteristics							
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	30	-	-	V	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V,V _{GS} =0V	-	-	1	μΑ	



Parameter	Symbol	Condition	Min	Тур	Max	Unit
Gate-Body Leakage Current	I _{GSS}	V_{GS} =±20 V , V_{DS} =0 V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS},I_{D}=250\mu A$	1.2	1.8	2.4	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =4A	-	13.5	17	mΩ
Diain-Source On-State Resistance		V _{GS} =4.5V, I _D =4A	-	16	22	mΩ
Dynamic Characteristics (Note4)						
Input Capacitance	C _{lss}	\/ -15\/\/ -0\/	-	784	-	PF
Output Capacitance	Coss	V_{DS} =15V, V_{GS} =0V, F=1.0MHz	-	109.4	-	PF
Reverse Transfer Capacitance	C _{rss}	r-1.0ivinz	-	93.8	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}	V_{DD} =15V, I_D =4A V_{GS} =10V, R_{GEN} =1 Ω	-	4	-	nS
Turn-on Rise Time	t _r		-	9	-	nS
Turn-Off Delay Time	t _{d(off)}		-	17	-	nS
Turn-Off Fall Time	t _f		-	6	-	nS
Total Gate Charge	Qg	V _{DS} =15V,I _D =4A, V _{GS} =10V	-	19.4	-	nC
Gate-Source Charge	Q _{gs}		-	2.5	-	nC
Gate-Drain Charge	Q _{gd}	VGS-10V	-	5.0	-	nC
Drain-Source Diode Characteristics						-
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =4A	-	-	1.2	V
Diode Forward Current (Note 2)	Is		-	-	8	Α

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board, $t \le 10$ sec.
- **3.** Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.
- **4.** Guaranteed by design, not subject to production



Typical Electrical and Thermal Characteristics

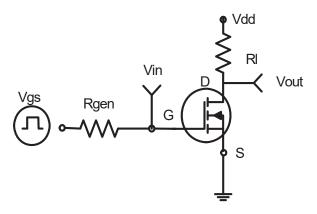


Figure 1 Switching Test Circuit

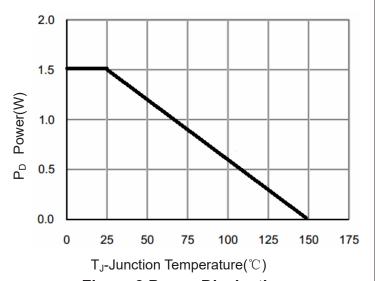


Figure 3 Power Dissipation

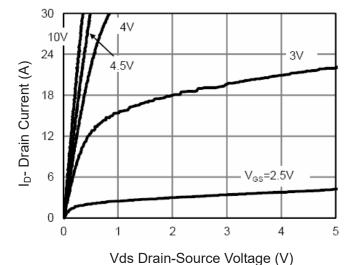


Figure 5 Output Characteristics

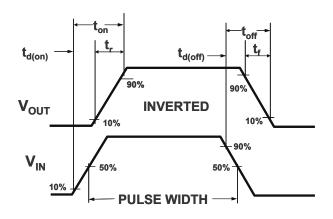


Figure 2 Switching Waveforms

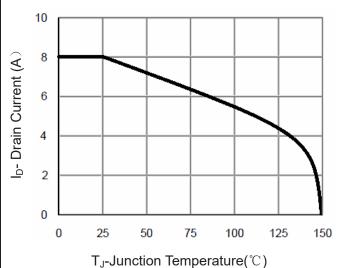


Figure 4 Drain Current

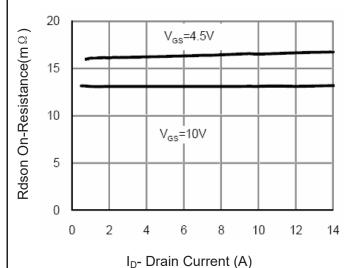


Figure 6 Drain-Source On-Resistance



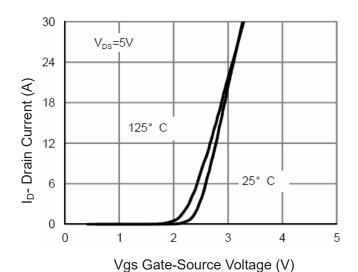
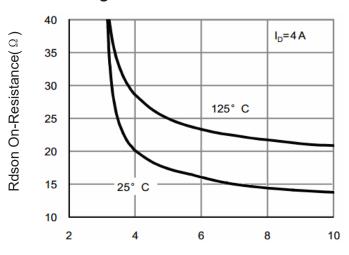


Figure 7 Transfer Characteristics



Vgs Gate-Source Voltage (V)

Figure 9 Rdson vs Vgs

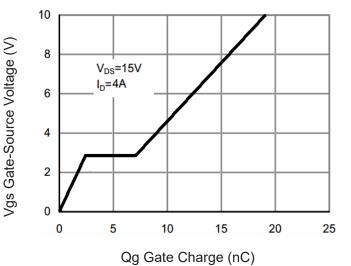


Figure 11 Gate Charge

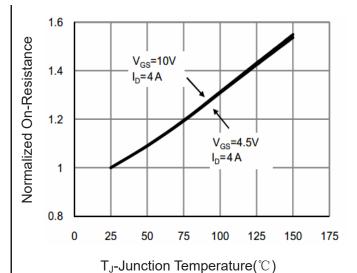
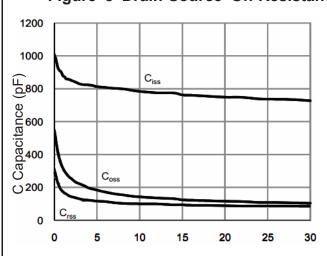


Figure 8 Drain-Source On-Resistance



Vds Drain-Source Voltage (V)

Figure 10 Capacitance vs Vds

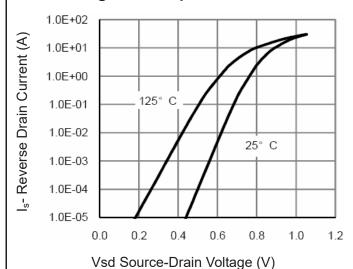
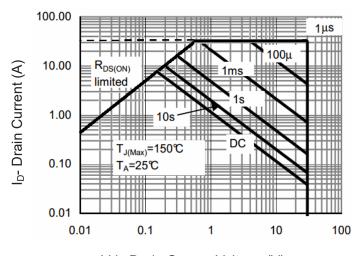


Figure 12 Source- Drain Diode Forward





Vds Drain-Source Voltage (V)

Figure 13 Safe Operation Area

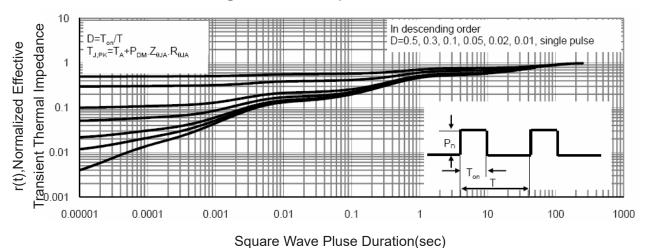


Figure 14 Normalized Maximum Transient Thermal Impedance